

REMARKS

Claims 1-8 are in this case. All claims are rejected.

35 U.S.C. §102(b) REJECTION (Greuter):

Claims 1-8 are rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent 5,414,403 issued May 9, 1995 to Greuter et al. (hereinafter "Greuter"). This rejection is respectfully traversed.

It is well established that a claimed invention is anticipated by a prior patent only if the patent discloses each and every limitation of the claim. In the present case, claim 1 calls for a device for compensating the effect of temperature changes in an electrical or electronic circuit. The device comprises a substrate having a pair of major surfaces, a plurality of thermistors embedded within the substrate, at least one of the thermistors comprising a columnar body of thermistor material extending substantially in the direction between the major surfaces; and metallization patterns on the major surfaces interconnecting the thermistors in a temperature compensating circuit.

The invention uses thermistors for temperature compensation of a circuit. That is, the resistance of the thermistors changes resistance in a compensating circuit with the temperature of the substrate for compensating the effect of temperature changes in an electrical or electronic circuit.

Greuter discloses a current limiting component. (Greuter, col. 1, line 67). This is a "power" component for use in a protective function, not as a temperature compensating element in a circuit. Greuter does not disclose the use of thermistors to compensate a circuit. Therefore Greuter does not anticipate claim 1 of the invention. Claims 2-8, as dependent on claim 1, are also not anticipated by Greuter.

35 U.S.C. §102(b) REJECTION (Abe):

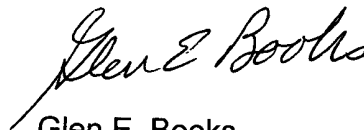
Claims 1-8 are also rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent 6,311,390 issued November 6, 2001 to Abe, et al. (hereinafter "Abe"). This rejection is respectfully traversed.

As previously discussed, claim 1 calls for a device comprising thermistors in a temperature compensating circuit for compensating the effect of temperature changes in an electrical or electronic circuit.

Abe discloses a method of producing thermistor chips. Thermistor chips are thermistor electronic components packaged as chips, or leadless components. The invention utilizes thermistors (the electronic component) embedded within a substrate to compensate the effects of temperature on circuitry. Abe does not disclose the use of thermistors for use in compensating circuitry, but rather the production of the thermistor component itself. Therefore Abe does not anticipate the invention. Claims 2-8, as dependent on claim 1, are also not anticipated by Abe.

In view of the foregoing, it is submitted that claims 1-8 patentably distinguish from the cited art. Accordingly, this case now fully complies with the provisions of 35 U.S.C. Section 102 and is now in condition for allowance. Reconsideration and favorable action in this regard are therefore earnestly solicited.

Respectfully submitted,



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